



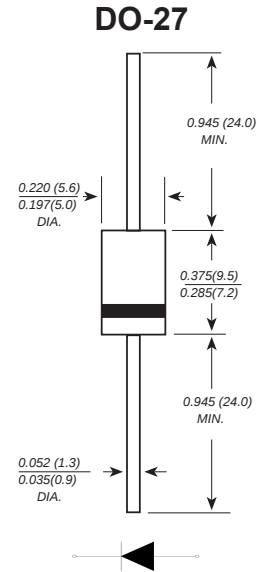
Axial Lead Rectifier Diode

Features

- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

- DO-27 Small Outline Plastic Package
- Polarity: Color band denotes cathode end
- Epoxy UL: 94V-0
- Mounting Position: Any



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	1N 5400G	1N 5401G	1N 5402G	1N 5403G	1N 5404G	1N 5405G	1N 5406G	1N 5407G	1N 5408G	Unit
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	300	400	500	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	210	280	350	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	300	400	500	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	3.0									A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	150.0									A
Maximum instantaneous forward voltage at 3.0A	V_F	1.0									V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	2.0 200									μA
Typical junction capacitance (Note1)	C_J	50.0									pF
Typical thermal resistance	R_{qJA}	45.0									$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150									$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.



Ratings and Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

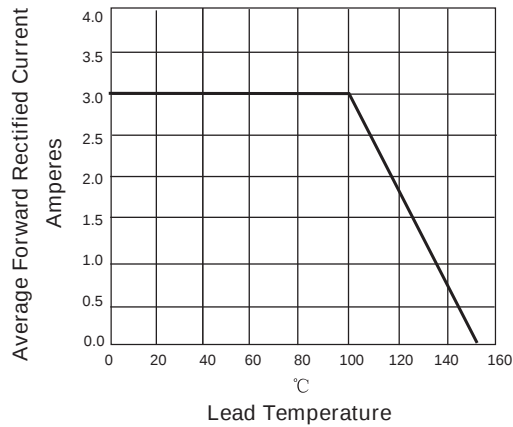


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

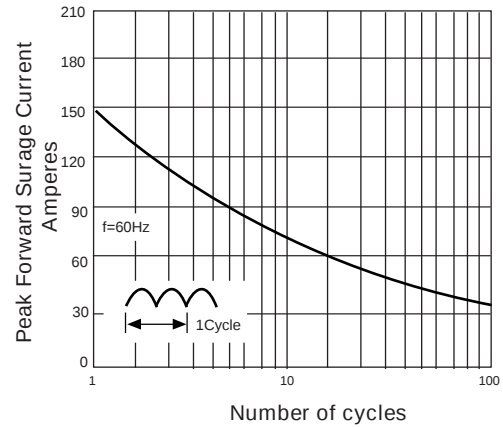


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

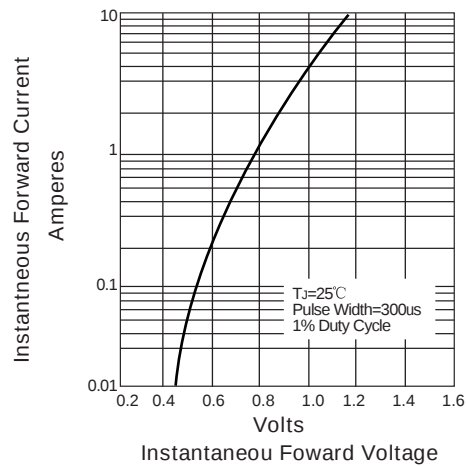
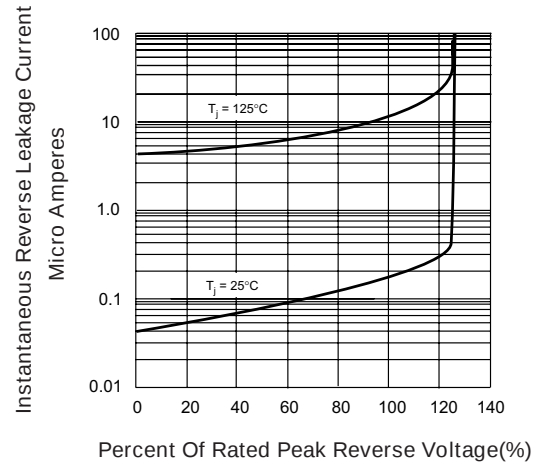
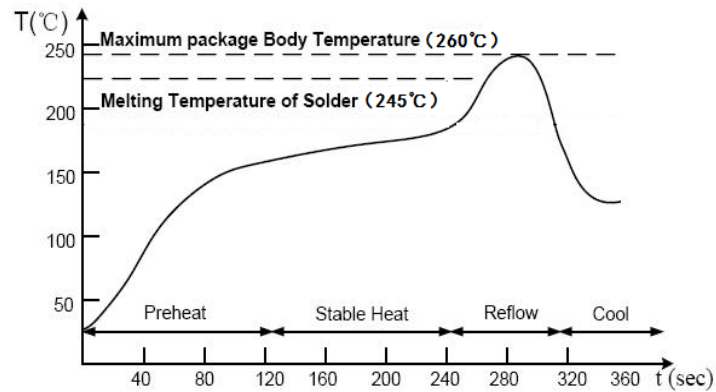


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS





Suggested Soldering Temperature Profile

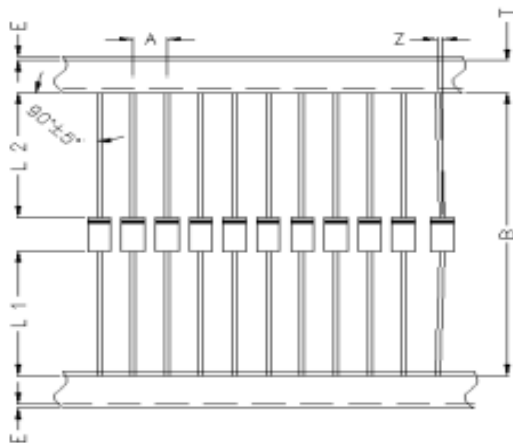


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Taping Specifications



Item	Symbol	Specifications(mm)
Component Pitch	A	10.0±0.5
Inner Tape Pitch	B	52.4±1.5
Component alignment	Z	1.2 Max
Tape width	T	6.0±0.5
Exposed adhesive	E	0.8 Max
Body eccentricity	L1-L2	1.0 Max

Ammunition Package Specifications

Package	Inner Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
D0-27	255*150*75	1.25	420*276*312	12.5